

Figure 1.

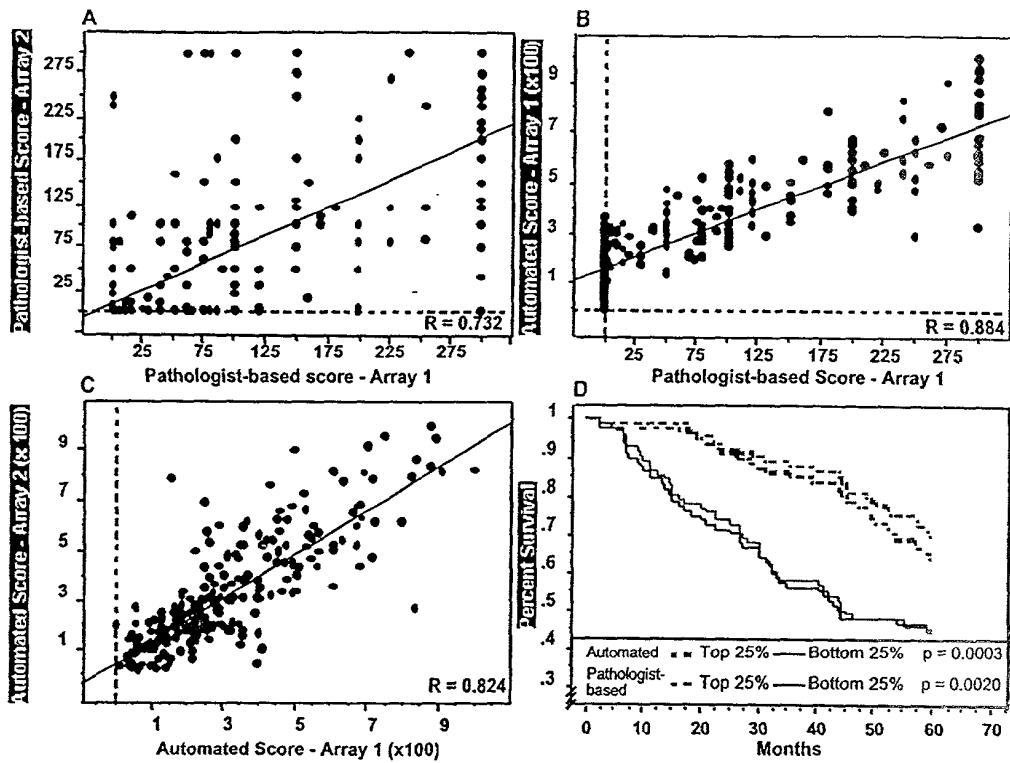


Figure 2

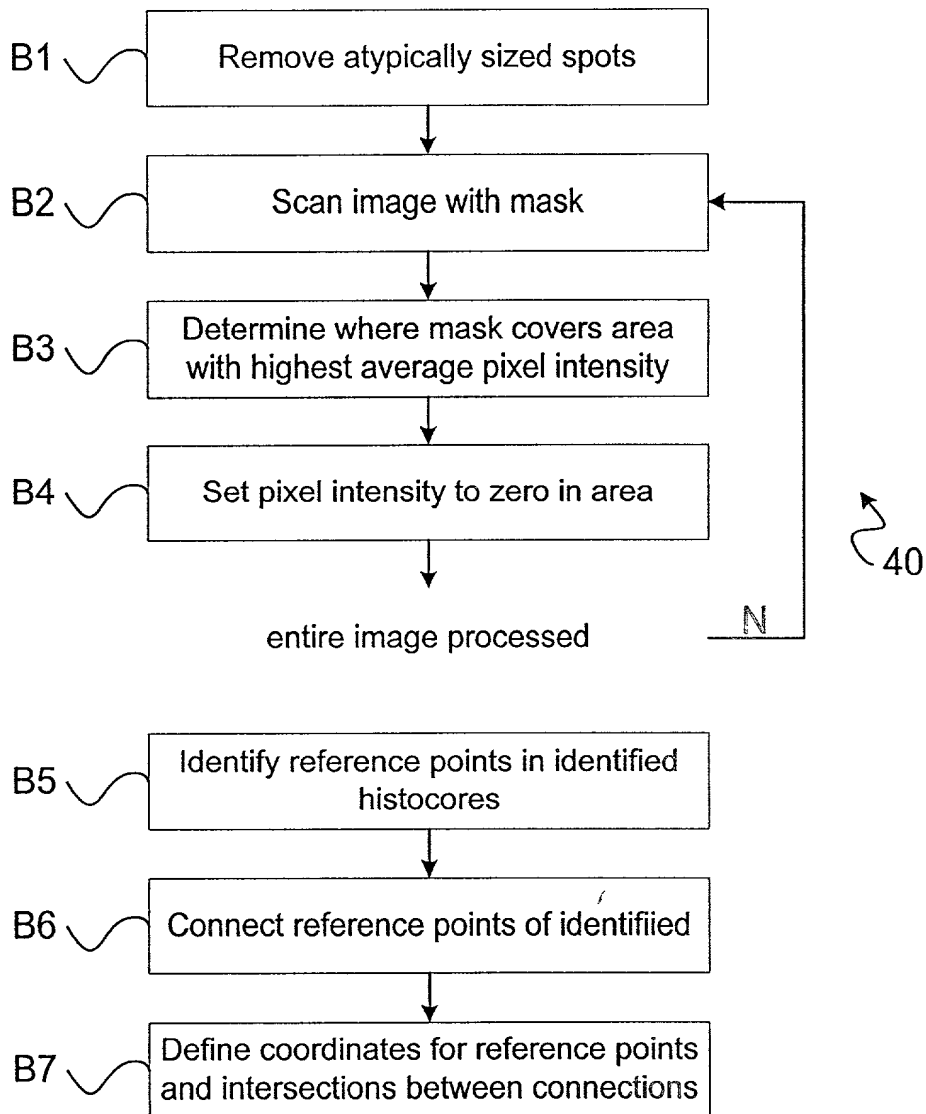


FIG. 3

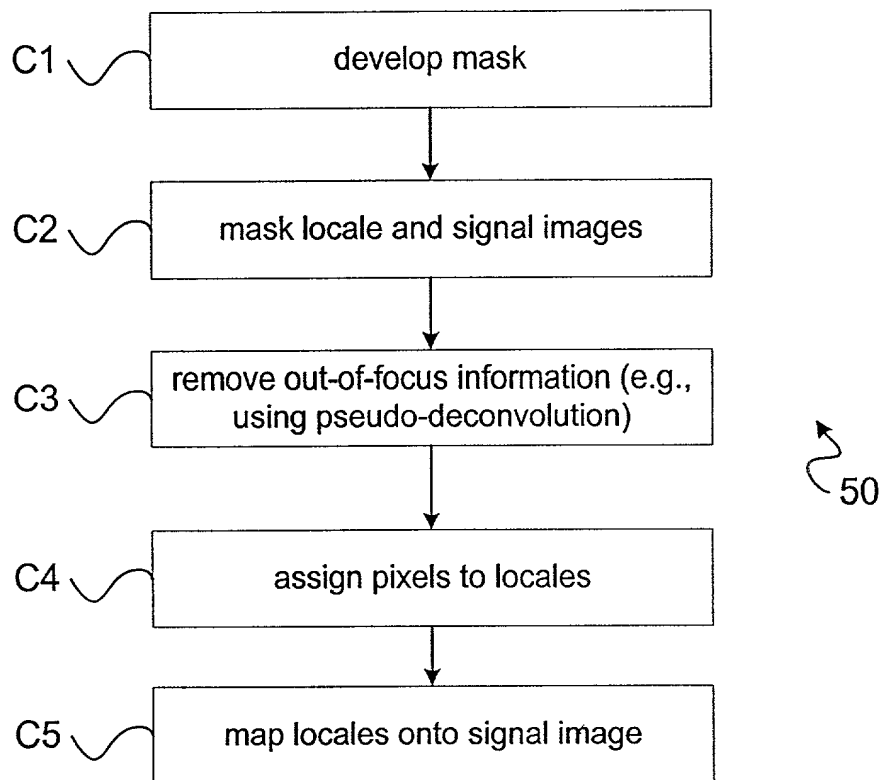


FIG. 4

100
↳

FIG. 5 is a schematic diagram of a device 100. The device 100 includes a substrate 110, a first layer 120, and a second layer 130. The first layer 120 is disposed on the substrate 110 and includes a grid of openings 120. The second layer 130 is disposed on the first layer 120 and includes a grid of openings 130. The openings 120 and 130 are arranged in a staggered fashion.

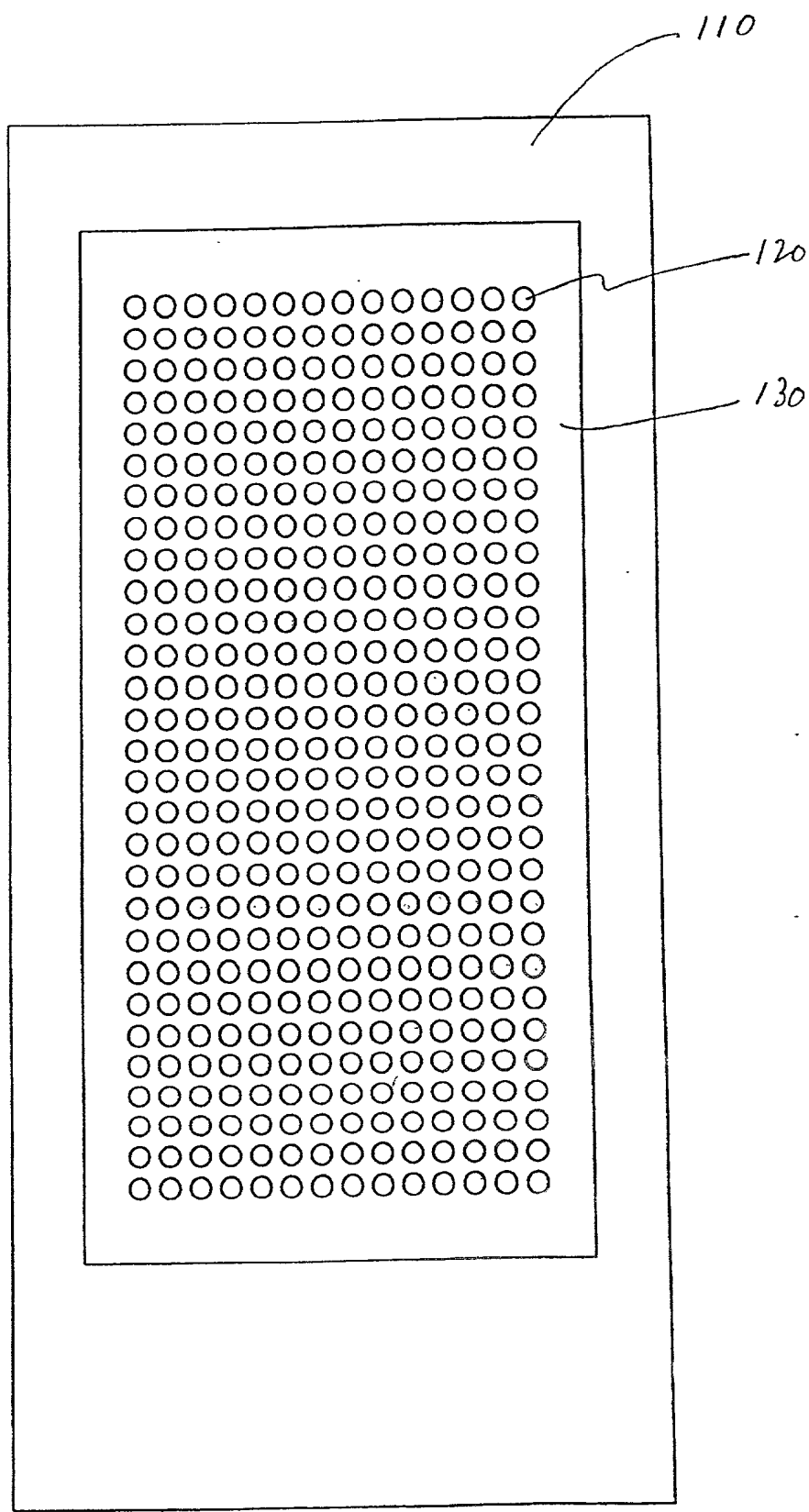


FIG. 5

FIG. 6 is a schematic diagram of a system 200 for processing a substrate 100. The system 200 includes a substrate 100, a processing chamber 210, a gas inlet 220, a gas outlet 230, a gas supply 240, a gas control system 250, and a gas distribution system 260. The gas inlet 220 is connected to the processing chamber 210. The gas outlet 230 is connected to the processing chamber 210. The gas supply 240 is connected to the gas inlet 220. The gas control system 250 is connected to the gas supply 240. The gas distribution system 260 is connected to the processing chamber 210.

200
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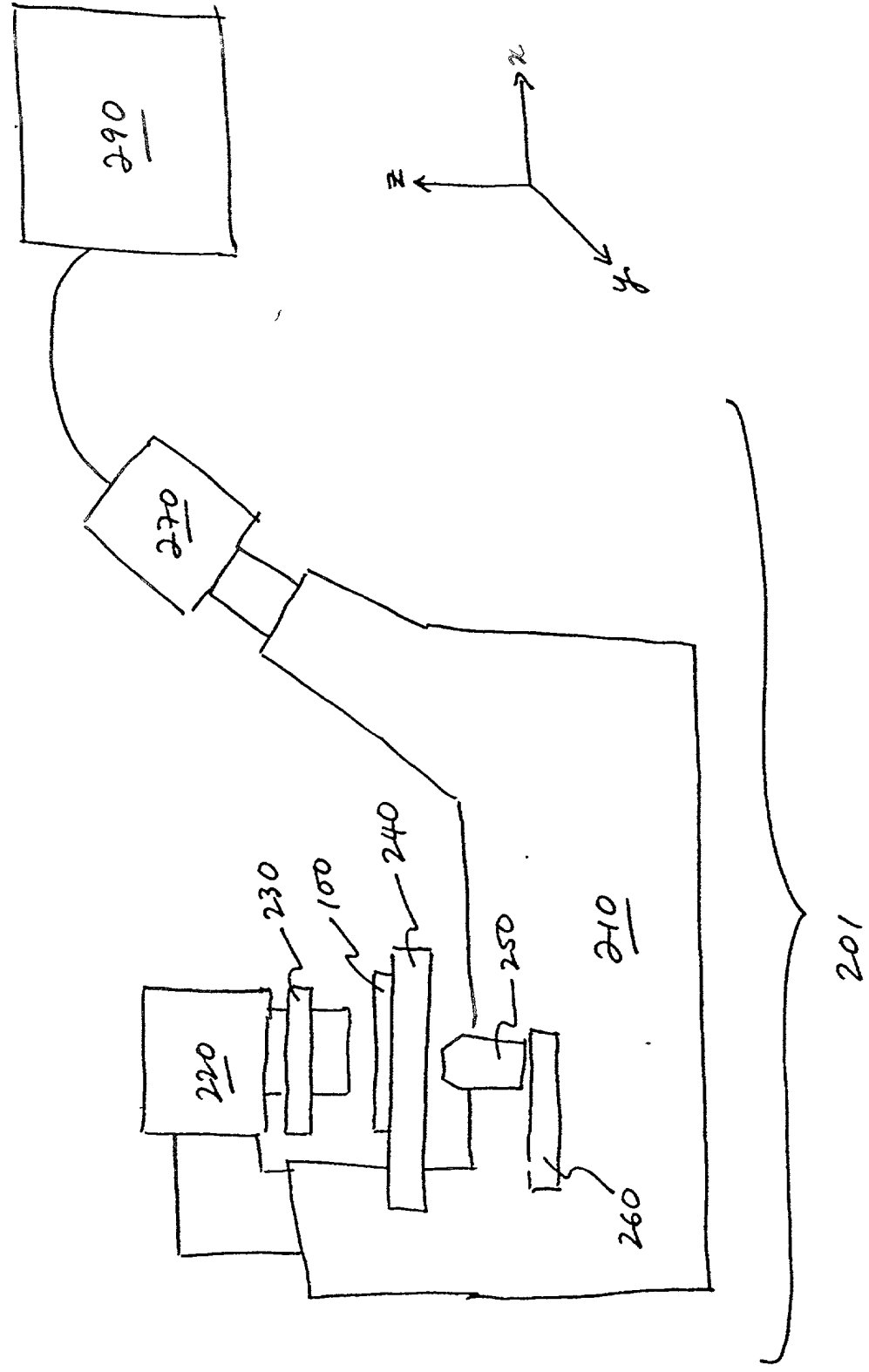


FIG. 6